



Material Content Data Sheet



Sales Product Name				BSC011N03LST		Issued		4. July 2019	
MA#				MA005349671					
Package				PG-TDSON-8-17		Weight*		119.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.077	0.90	0.90	9031	9031	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		317		
wire	non noble metal	copper	7440-50-8	37.762	31.68	31.72	316755	317167	
	noble metal	gold	7440-57-5	0.041	0.03	0.03	343	343	
encapsulation	organic material	carbon black	1333-86-4	0.132	0.11		1106		
	plastics	epoxy resin	-	5.143	4.31		43137		
leadfinish	inorganic material	silicondioxide	60676-86-0	38.679	32.46	36.88	324449	368692	
	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12177	12177	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1388	1388	
solder	non noble metal	tin	7440-31-5	0.030	0.02		248		
	noble metal	silver	7440-22-4	0.037	0.03		310		
heat sink clip	non noble metal	lead	7439-92-1	1.410	1.18	1.23	11827	12385	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	zinc	7440-66-6	0.026	0.02		222		
	non noble metal	iron	7439-89-6	0.529	0.44		4438		
heatspreader	non noble metal	copper	7440-50-8	21.482	18.02	18.49	180199	184914	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.013	0.01		113		
	non noble metal	iron	7439-89-6	0.269	0.23		2254		
	non noble metal	copper	7440-50-8	10.909	9.15	9.39	91508	93903	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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